

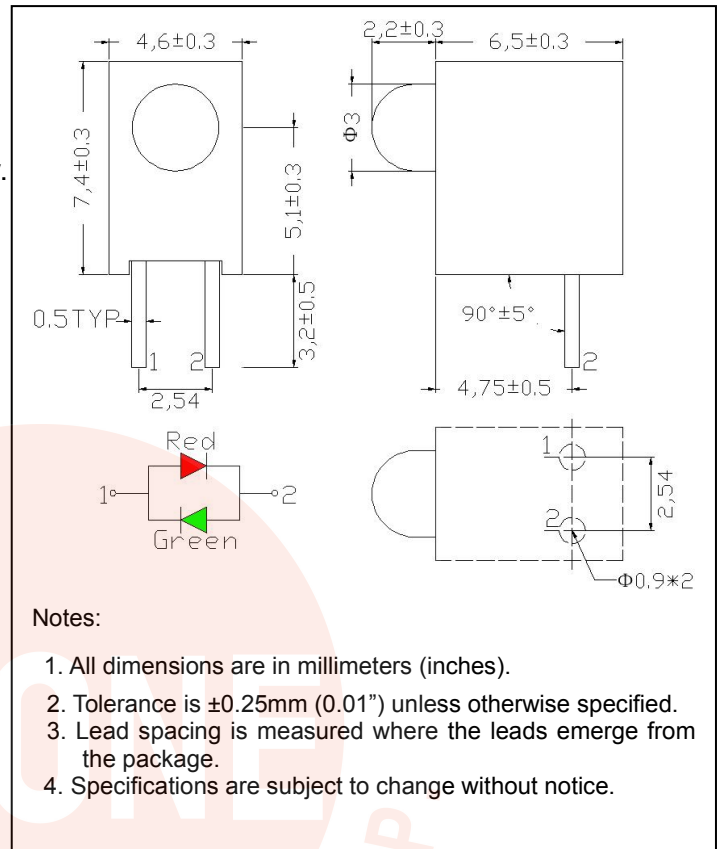
● Features:

1. Chip material: AlInGaP(Red)/InGaN(Green)
2. Emitted color : Red/Green
3. Lens Appearance :White Diffused
4. Designed for ease in circuit board assembly.
5. Black case enhance contrast ratio.
6. Solid state light source.
7. Reliable and rugged.
8. This product don't contained restriction substance, compliance RoHS standard.

● Applications:

1. TV set
2. Monitor
3. Telephone
4. Computer
5. Circuit board

● Package dimensions



● Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Red	Green	Unit
Power Dissipation	Pd	70	80	mW
Forward Current	I _F	30	30	mA
Peak Forward Current*1	I _{FP}	120	120	mA
Reverse Voltage	V _R	1		V
Operating Temperature	Topr	-40°C~85°C		
Storage Temperature	Tstg	-40°C~85°C		
Soldering Temperature	Tsol	260°C max (for 5 seconds)		
Hand Soldering Temperature	Tsol	350°C max(for 3 seconds)		

*1Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

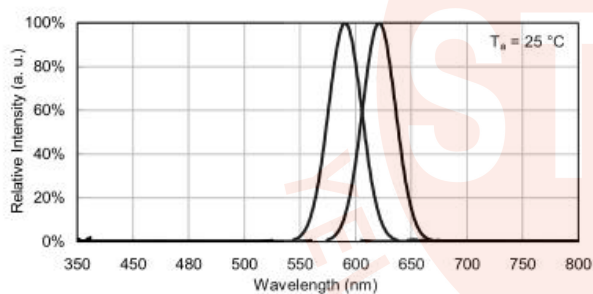
● Electrical and optical characteristics(Ta=25°C)

Parameter	Symbol	Condition	Color	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F=20\text{mA}$	Red Green	1.8 2.0	2.1 2.3	2.4 2.6	V
Luminous Intensity	I_v	$I_F=20\text{mA}$	Red Green	10 5	40 10	70 20	mcd
Reverse Current	I_R	$V_R=5\text{V}$	Red Green	-	-	10 10	μA
Peak Wave Length	λ_p	$I_F=20\text{mA}$	Red Green	-	644 -	-	nm
Dominant Wave Length	λ_d	$I_F=20\text{mA}$	Red Green	635 567	640 570	645 573	nm
Spectral Line Half-width	$\Delta\lambda$	$I_F=20\text{mA}$	Red Green	-	30 30	-	nm
Viewing Angle	$2\theta_{1/2}$	$I_F=20\text{mA}$	Red Green	-	90 90	-	deg

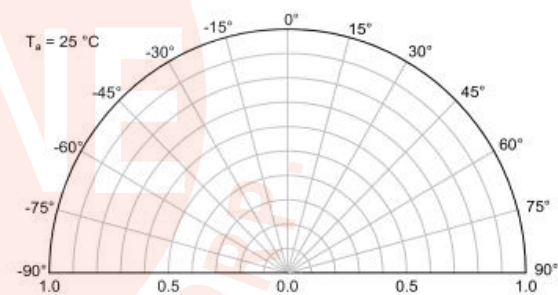
● Typical electro-optical characteristics curves

TECHNICAL DATA

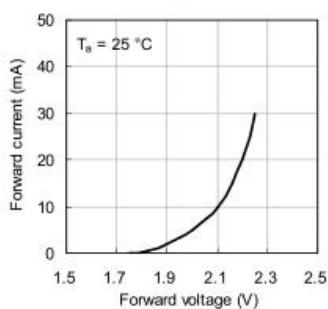
RELATIVE INTENSITY vs. WAVELENGTH



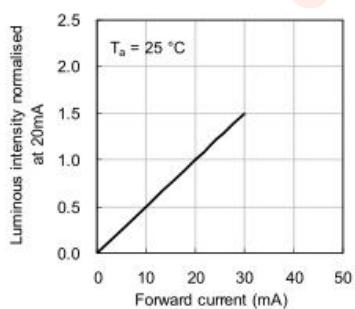
SPATIAL DISTRIBUTION



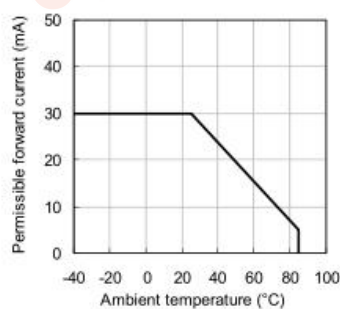
Forward Current vs. Forward Voltage



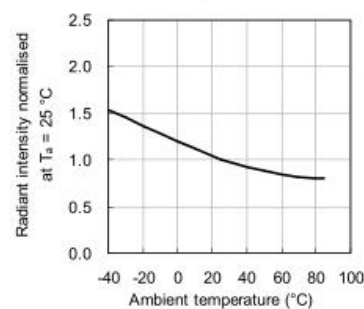
Luminous Intensity vs. Forward Current



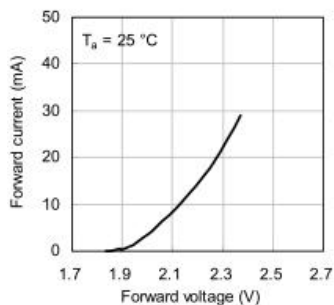
Forward Current Derating Curve



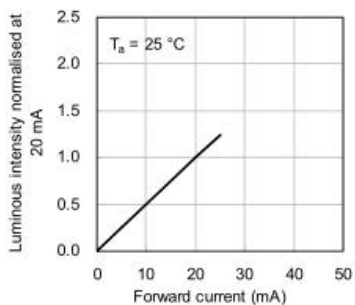
Luminous Intensity vs. Ambient Temperature



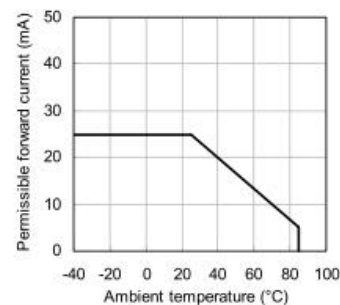
Forward Current vs. Forward Voltage



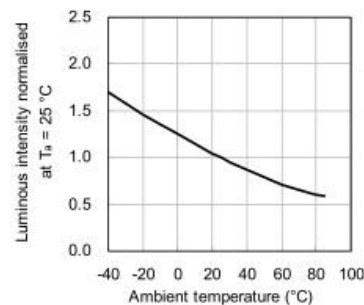
Luminous Intensity vs. Forward Current



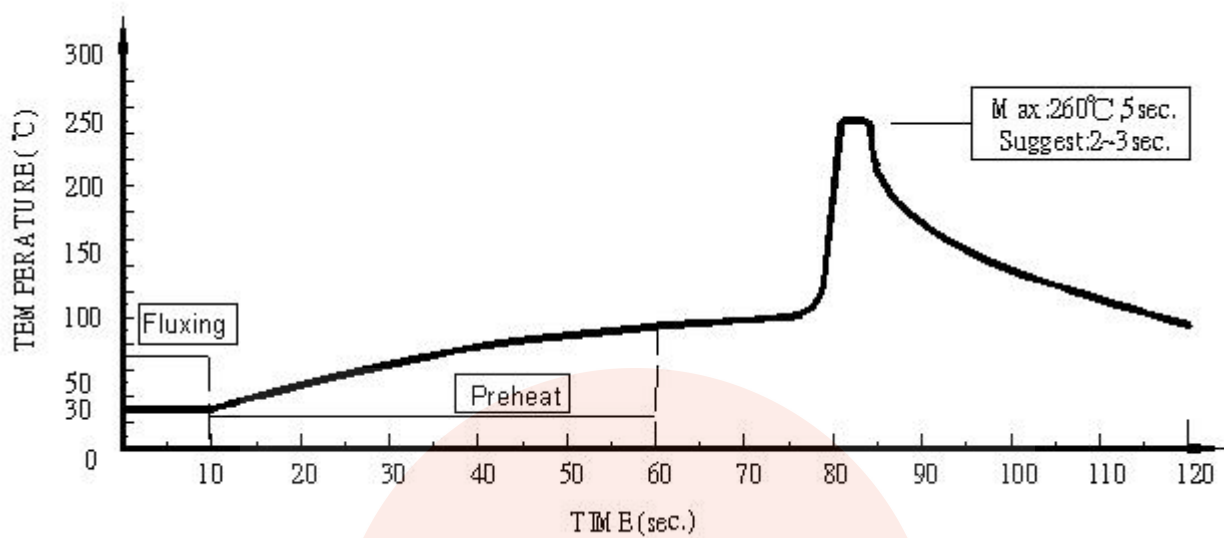
Forward Current Derating Curve



Luminous Intensity vs. Ambient Temperature



● DIP Soldering



1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature, especially during soldering
2. DIP soldering and hand soldering should not be done more than one time.
3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temperature.
4. Avoid rapid cooling during temperature ramp-down process
5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

● IRON Soldering

A: Max: 350°C Within 3 sec. One time only.

B: The products of 3mm without flange, welding condition of flat plate PCB Max: 350°C

Within 2 sec. One time only

